

ABSTRACT OF THE DISCLOSURE

A polyimide film of the present invention is a polyimide film having a dynamic viscoelasticity whose $\tan \delta$ peak is located in a range of not less than 310°C but not more than 410°C, and whose $\tan \delta$ value at 300°C is not more than 0.05, or a polyimide film prepared by copolymerizing (a) an acid dianhydride component including a biphenyltetracarboxylic dianhydride and a pyromellitic dianhydride, and (b) a diamine component, and the polyimide film having such an etching speed that one side thereof is etched with a 1N potassium hydroxide solution at an etching speed of 0.1 μ m/minute (one side) or higher. The polyimide film of the present invention possesses film properties that are necessary for use in an electronic raw material for flexible printed circuit boards and the like, and is suitable as an electronic raw material.